

# Metal Foil Current Sense Resistors, Low Value (Down to 0.001 $\Omega$ )





#### **FEATURES**

- Ultra low sensing resistance
- Low TCR (down to 50 ppm/°C)
- Chip size down to 0402, minimizing board space
- Sulfur resistant
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



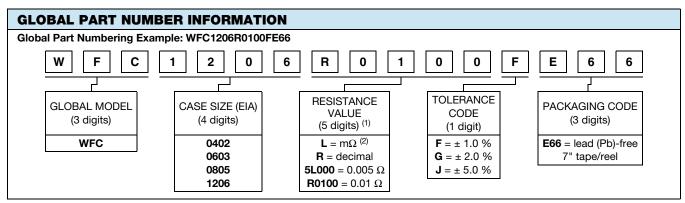
ROHS

HALOGEN FREE GREEN (5-2008)

#### **APPLICATIONS**

- Switching power supply
- Voltage regulation module
- DC/DC converter, adaptor, battery pack, charger
- Pad and cell phone
- Power management

STANDARD ELECTRICAL SPECIFICATIONS									
GLOBAL MODEL	SIZE	POWER RATING W	TOLERANCE %	RESISTANCE VALUE RANGE $\Omega$	WEIGHT (typical) g/1000 pieces				
WFC0402	0402	0.125	± 1, ± 2, ± 5	0.003 to 0.05	1.1				
WEC0603	0603	0.33	± 1, ± 2, ± 5	0.001 to 0.005	3.3				
WFC0603	0603	0.25	± 1, ± 2, ± 5	0.0051 to 0.03	3.3				
WFC0805	0805	0.50	± 1, ± 2, ± 5	0.001 to 0.04	6.8				
WFC1206	1206	1.0	± 1, ± 2, ± 5	0.001 to 0.05	17.4				
	1206	0.5	± 1, ± 2, ± 5	0.100 to 0.18	17.4				



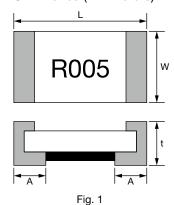
#### Notes

- (1) Resistance values are available per E12 and E24 decades; www.vishay.com/doc?28372
- $^{(2)}$  Use "L" for resistance values < 0.01  $\Omega$



TECHNICAL SPECIFICATIONS									
PARAMETER	UNIT	RESISTOR CHARACTERISTICS							
PARAMETER	UNII	WFC0402	WFC0603	WFC0805	WFC1206				
	ppm/°C	-	$\pm$ 100 for 1 m $\Omega$ to 5 m $\Omega$	-	-				
Temperature coefficient		$\pm$ 150 for 3 m $\Omega$ to 7 m $\Omega$	$\pm$ 150 for 5.1 m $\Omega$ to 9 m $\Omega$	$\pm$ 100 for 1 m $\Omega$ to 10 m $\Omega$	$\pm$ 100 for 1 m $\Omega$ to 10 m $\Omega$				
		$\pm$ 100 for 8 m $\Omega$ to 50 m $\Omega$	$\pm$ 75 for 10 m $\Omega$ to 30 m $\Omega$	$\pm$ 50 for 10.1 m $\Omega$ to 40 m $\Omega$	$\pm$ 50 for 10.1 m $\Omega$ to 180 m $\Omega$				
Operating temperature range	ů	-55 to +170							
Maximum working voltage	V	$(P \times R)^{1/2}$							
Maximum element temperature	°C	170							

## **DIMENSIONS** in inches (millimeters)



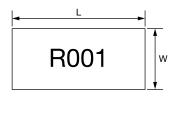




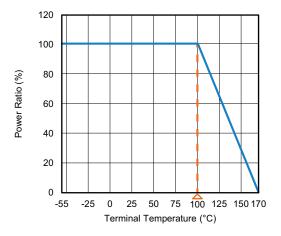
Fig. 2

TYPE	RESISTANCE		DIMENSIONS FIG.			
(INCH SIZE)	RANGE (m $\Omega$ )	L	L W t		Α	DIMENSIONS FIG.
WEC0402	3 to 7	1.00 ± 0.10	00 040 055 040 045 040		$0.35 \pm 0.10$	1
WFC0402	7.1 to 50	1.00 ± 0.10	0.55 ± 0.10	$0.45 \pm 0.10$	0.25 ± 0.10	1
WFC0603	1 to 5	1.60 ± 0.10	0.95 ± 0.25	$0.60 \pm 0.25$	$0.55 \pm 0.20$	2
	5.1 to 30	1.00 ± 0.10	$0.80 \pm 0.10$	0.55 ± 0.15	$0.30 \pm 0.20$	1
WFC0805	1 to 5	2.10 ± 0.20	1.40 ± 0.20	0.60 max.	$0.60 \pm 0.20$	2
WFC0003	5.1 to 40	$2.00 \pm 0.20$	1.30 ± 0.15	$0.70 \pm 0.15$	$0.45 \pm 0.20$	1
WE04000	1 to 3	3.10 ± 0.20	1.55 ± 0.20	0.75 ± 0.25	1.30 ± 0.20	2
WFC1206	3.1 to 180	3.10 ± 0.20	$1.55 \pm 0.20$	0.80 ± 0.15	0.55 ± 0.20	1

#### Note

• 0402 has no marking; 0603, 0805, 1206 marking shows two digits for resistance

## **DERATING**





## **PERFORMANCES**

ENV	ENVIRONMENTAL PERFORMANCE								
NO.	ITEM	TEST CONDITION	SPECIFICATION						
1	Short time overload	5 times rated power for 5 seconds (JIS-C5202-5.5)	$\Delta R$ : ± (1 % + 0.0005 $\Omega$ )						
2	Temperature coefficient of resistance (TCR)	+25 °C / +125 °C (JIS-C5202-5.2) TCR (ppm/°C) = $\frac{\Delta R}{R \times \Delta t} \times 10^6$	Refer to Electrical Specification						
3	Damp heat with load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90 % to 95 % and a temperature of 40 °C ± 2 °C for the period of 1000 hours with applying rated power 1.5 hours ON and 0.5 hour OFF. (MIL-STD-202, method 103)	ΔR: ± (1 % + 0.0005 Ω)						
4	High temperature exposure	The chip (mounted on board) is exposed in the heat chamber 125 °C $\pm$ 3 °C for 1000 hours. (JIS-C5202-7.2)	ΔR: ± (1 % + 0.0005 Ω)						
5	Load life	Apply rated power at 70 °C ± 2 °C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	$\Delta R$ : ± (1 % + 0.0005 $\Omega$ )						
6	Rapid change of temperature	The chip (mounted on board) is exposed, -55 °C $\pm$ 3 °C (30 min.) / +155 °C $\pm$ 2 °C (30 min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature +155 ( $\pm$ 2) °C +25 ( $\pm$ 2) °C +25 ( $\pm$ 3) °C 1 cycle	ΔR: ± (1 % + 0.0005 Ω)						

FUN	FUNCTION PERFORMANCE							
NO.	ITEM	TEST CONDITION	SPECIFICATION					
1	Bending strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2 mm (+0.2 / -0 mm) illustrated in the figure below and hold for 10 s ± 1 s. (JIS-C5202-6.1)  Position before bend  Testing printed circuit board	$\Delta R$ : ± (1 % + 0.0005 $\Omega$ )					
2	Solvent resistance	Complete immersion of specimens in isopropyl alcohol for 3 (+5, -0) min. 25 $^{\circ}$ C $_{\pm}$ 5 $^{\circ}$ C. (MIL-STD-202, method 215)	Verify marking permanency. (not required for laser etched parts or parts with no marking)					
3	Resistance to solder heat	The specimen chip shall be immersed into the flux specified in the solder bath 260 $^{\circ}$ C $\pm$ 5 $^{\circ}$ C for 10 s $\pm$ 1 s. (MIL-STD-202, method 210)	$\Delta R$ : ± (1 % + 0.0005 $\Omega$ )					



FUN	FUNCTION PERFORMANCE							
NO.	ITEM	TEST CONDITION	SPECIFICATION					
4	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath 235 °C $\pm$ 5 °C for 2 s $\pm$ 0.5 s. It shall be immersed to a point 10 mm from its root. (Sn96.5 / Ag3.0 / Cu0.5) (JIS-C5 202-6.11)  Molten solder  Specimen SMD $ h = 10 \text{ mm} $ $ H = 10 \text{ mm min.} $	Solder shall be covered 95 % or more of the electrode area.					

#### **Notes**

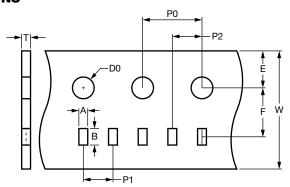
- 0.5 W with total solder pad trace size of 100 mm<sup>2</sup>. The surface temperature of component should below 100 °C
- 1.0 W with total solder pad trace size of 100 mm<sup>2</sup>. The surface temperature of component should below 100 °C

TAPE PACKAGING SPECIFICATIONS							
REEL							
MODEL	TAPE WIDTH	DIAMETER	PIECES/REEL				
WFC0402	Embossed paper tape	178 mm / 7"	10 000				
WFC0603, WFC0805, WFC1206	Embossed paper tape	178 mm / 7"	5000				

#### Note

Embossed carrier tape per EIA (EIAJ)

## PAPER TAPE SPECIFICATIONS



TYPE	RESISTANCE	CARRIER DIMENSIONS (in millimeters)									
RANGE	Α	В	E	F	W	P0	P1	P2	D0	Т	
WFC0402	3 m $\Omega$ to 50 m $\Omega$	$0.7 \pm 0.05$	$1.2 \pm 0.05$	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	$4.0 \pm 0.1$	$2.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	$0.6 \pm 0.1$
WFC0603	1 m $\Omega$ to 5 m $\Omega$	1.4 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	$0.75 \pm 0.1$
WFC0603	5.1 m $\Omega$ to 30 m $\Omega$	1.1 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	$0.70 \pm 0.1$
WFC0805	1 m $\Omega$ to 5 m $\Omega$	2.4 ± 0.1	1.9 ± 0.1	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	0.75 ± 0.1
WFC0805	5.1 m $\Omega$ to 40 m $\Omega$	1.6 ± 0.1	2.4 ± 0.1	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	$0.97 \pm 0.1$
WFC1206	1 m $\Omega$ to 3 m $\Omega$	2.0 ± 0.1	$3.6 \pm 0.1$	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	$4.0 \pm 0.1$	$4.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	0.87 ± 0.1
WFC1206	3.1 m $\Omega$ to 180 m $\Omega$	$2.0 \pm 0.1$	$3.6 \pm 0.1$	1.75 ± 0.1	$3.5 \pm 0.05$	$8.0 \pm 0.2$	4.0 ± 0.1	$4.0 \pm 0.1$	$2.0 \pm 0.05$	1.55 ± 0.05	0.97 ± 0.1

#### Notes

Revision: 14-Jul-2023

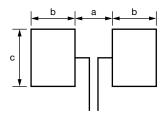
- Embossed carrier tape per EIA (EIAJ)
- Additional packaging details at <a href="www.vishay.com/doc?20051">www.vishay.com/doc?20051</a>



### **STORAGE CONDITIONS**

Temperature: 5 °C to 35 °C, humidity: 40 % to 75 %

#### RECOMMENDED SOLDER PAD LAYOUT



TYPE	PAD LAYOUT DIMENSIONS (in millimeters)					
IIFE	а	b	С			
0402 (3 mΩ to 7 mΩ)	0.30	0.60	0.60			
0402 (7.1 m $\Omega$ to 50 m $\Omega$ )	0.50	0.50	0.60			
0603 (1 m $\Omega$ to 5 m $\Omega$ )	0.30	1.10	1.50			
0603 (5.1 m $\Omega$ to 9 m $\Omega$ )	0.60	0.90	1.00			
0603 (9.1 m $\Omega$ to 30 m $\Omega$ )	0.90	0.70	1.00			
0805 (1 m $\Omega$ to 5 m $\Omega$ )	0.80	1.60	1.45			
0805 (5.1 m $\Omega$ to 40 m $\Omega$ )	1.20	1.20	1.40			
1206 (1 mΩ to 3 mΩ)	0.40	1.80	2.20			
1206 (3.1 m $\Omega$ to 180 m $\Omega$ )	2.20	1.30	1.80			

#### Note

• Recommend to use the steel plate which thickness > 100 µm to avoid the insufficient solder height

### **SOLDERING RECOMMENDATIONS**

- Peak reflow temperatures and durations:
  - IR reflow peak = 260 °C max. for 10 s
  - Wave solder = 260 °C max. for 10 s
- Compatible with lead and lead (Pb)-free solder reflow processes
- Recommended IR reflow profile for surface mount devices: www.vishay.com/doc?31052



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